

# KM23C3200C

# CMOS MASK ROM

## 32M-Bit (2Mx16) CMOS MASK ROM

### FEATURES

- 2,097,152x16 bit organization
- Fast access time : 100ns(Max.)
- Supply voltage : single +5V
- Current consumption
  - Operating : 50mA(Max.)
  - Standby : 50µA(Max.)
- Fully static operation
- All inputs and outputs TTL compatible
- Three state outputs
- Package
  - KM23C32000C : 42-DIP-600

### GENERAL DESCRIPTION

The KM23C32000C is a fully static mask programmable ROM organized 2,097,152x16 bit. It is fabricated using silicon-gate CMOS process technology.

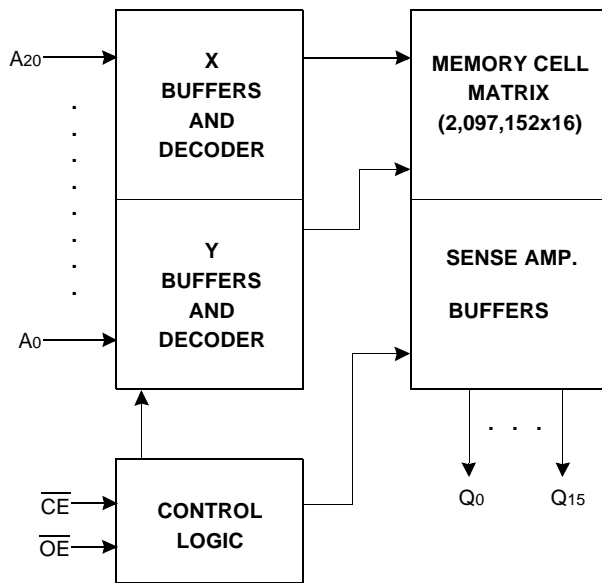
This device operates with a 5V single power supply, and all inputs and outputs are TTL compatible.

Because of its asynchronous operation, it requires no external clock assuring extremely easy operation.

It is suitable for use in program memory of microprocessor and data memory, character generator.

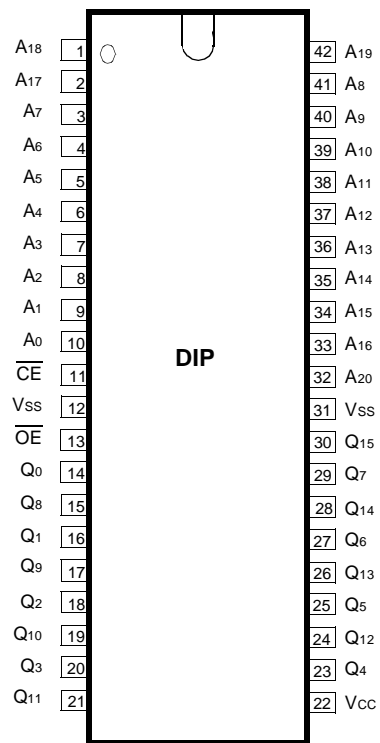
The KM23C32000C is packaged in a 42-DIP.

### FUNCTIONAL BLOCK DIAGRAM



Pin Name	Pin Function
A0 - A20	Address Inputs
Q0 - Q15	Data Outputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
Vcc	Power (+5V)
Vss	Ground

### PIN CONFIGURATION



KM23C32000C

**KM23C32000C****CMOS MASK ROM****ABSOLUTE MAXIMUM RATINGS**

Item	Symbol	Rating	Unit
Voltage on Any Pin Relative to V <sub>SS</sub>	V <sub>IN</sub>	-0.3 to +7.0	V
Temperature Under Bias	T <sub>BIAS</sub>	-10 to +85	°C
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C

**NOTE** : Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**RECOMMENDED OPERATING CONDITIONS**(Voltage reference to V<sub>SS</sub>, T<sub>A</sub>=0 to 70°C)

Item	Symbol	Min	Typ	Max	Unit
Supply Voltage	V <sub>CC</sub>	4.5	5.0	5.5	V
Supply Voltage	V <sub>SS</sub>	0	0	0	V

**DC CHARACTERISTICS**

Parameter	Symbol	Test Conditions	Min	Max	Unit
Operating Current	I <sub>CC</sub>	$\overline{CE}=\overline{OE}=V_{IL}$ , all outputs open	-	50	mA
Standby Current(TTL)	I <sub>SB1</sub>	$\overline{CE}=V_{IH}$ , all outputs open	-	1	mA
Standby Current(CMOS)	I <sub>SB2</sub>	$\overline{CE}=V_{CC}$ , all outputs open	-	50	μA
Input Leakage Current	I <sub>LI</sub>	V <sub>IN</sub> =0 to V <sub>CC</sub>	-	10	μA
Output Leakage Current	I <sub>LO</sub>	V <sub>OUT</sub> =0 to V <sub>CC</sub>	-	10	μA
Input High Voltage, All Inputs	V <sub>IH</sub>		2.2	V <sub>CC</sub> +0.3	V
Input Low Voltage, All Inputs	V <sub>IL</sub>		-0.3	0.8	V
Output High Voltage Level	V <sub>OH</sub>	I <sub>OH</sub> =-400μA	2.4	-	V
Output Low Voltage Level	V <sub>OL</sub>	I <sub>OL</sub> =2.1mA	-	0.4	V

**NOTE** : Minimum DC Voltage(V<sub>IL</sub>) is -0.3V on input pins. During transitions, this level may undershoot to -2.0V for periods <20ns.  
Maximum DC voltage on input pins(V<sub>IH</sub>) is V<sub>CC</sub>+0.3V which, during transitions, may overshoot to V<sub>CC</sub>+2.0V for periods <20ns.

**MODE SELECTION**

$\overline{CE}$	$\overline{OE}$	Mode	Data	Power
H	X	Standby	High-Z	Standby
L	H	Operating	High-Z	Active
L	L	Operating	Dout	Active

**CAPACITANCE**(T<sub>A</sub>=25°C, f=1.0MHz)

Item	Symbol	Test Conditions	Min	Max	Unit
Output Capacitance	C <sub>OUT</sub>	V <sub>OUT</sub> =0V	-	12	pF
Input Capacitance	C <sub>IN</sub>	V <sub>IN</sub> =0V	-	12	pF

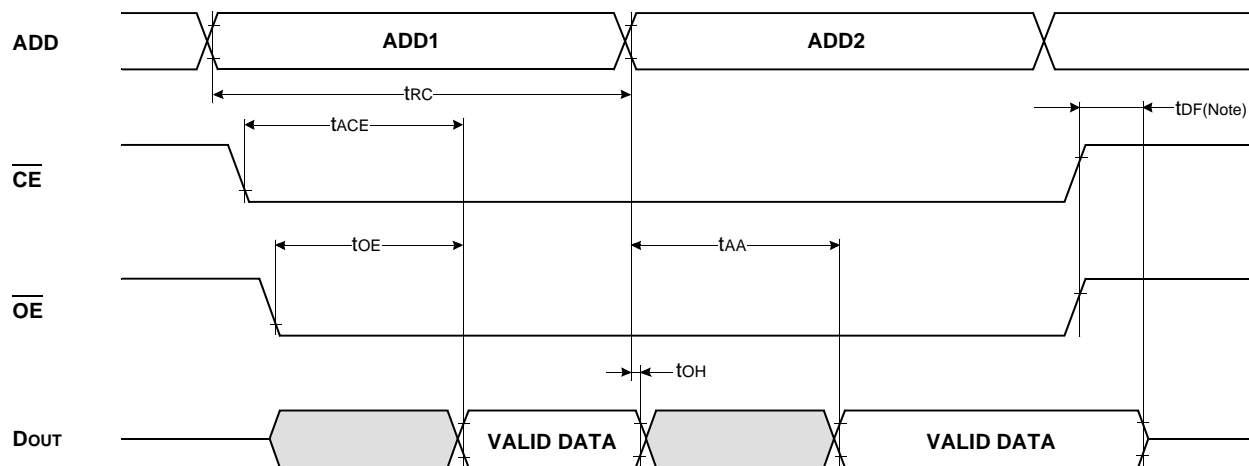
**NOTE** : Capacitance is periodically sampled and not 100% tested.

**KM23C32000C****CMOS MASK ROM****AC CHARACTERISTICS**( $T_A=0^{\circ}\text{C}$  to  $+70^{\circ}\text{C}$ ,  $V_{CC}=5\text{V}\pm 10\%$ , unless otherwise noted.)**TEST CONDITIONS**

Item	Value
Input Pulse Levels	0.6V to 2.4V
Input Rise and Fall Times	10ns
Input and Output timing Levels	0.8V and 2.0V
Output Loads	1 TTL Gate and $C_L=100\text{pF}$

**READ CYCLE**

Item	Symbol	KM23C32000C-10		KM23C32000C-12		KM23C32000C-15		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	t <sub>RC</sub>	100		120		150		ns
Chip Enable Access Time	t <sub>ACE</sub>		100		120		150	ns
Address Access Time	t <sub>AA</sub>		100		120		150	ns
Output Enable Access Time	t <sub>OE</sub>		50		60		70	ns
Output or Chip Disable to Output High-Z	t <sub>DF</sub>		20		20		30	ns
Output Hold from Address Change	t <sub>OH</sub>	0		0		0		ns

**TIMING DIAGRAM****READ**

**NOTE :** t<sub>DF</sub> is defined as the time at which the outputs achieve the open circuit condition and is not referenced to V<sub>OH</sub> or V<sub>OL</sub> level.

